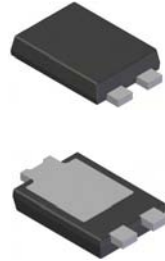
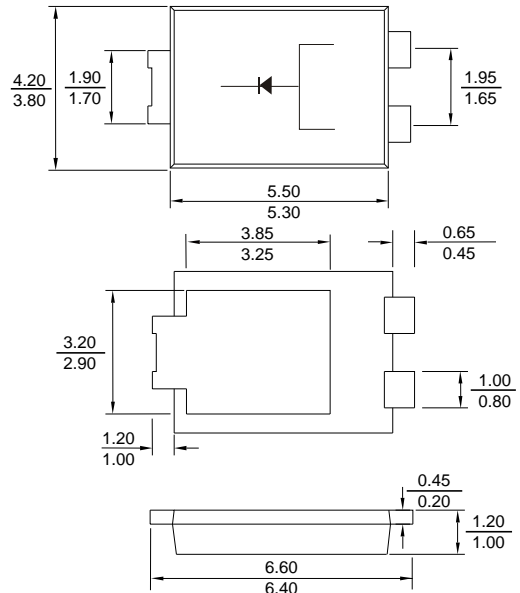


Features

- Schottky Barrier Chip
- Bypass Diodes for Solar Panels
- High Junction Temperature
- High Thermal Reliability
- Patented Super Barrier Rectifier Technology
- High Forward Surge Capability
- Ultra Low Power Loss, High Efficiency
- Excellent High Temperature Stability



TO-277B



Dimensions in millimeters

Mechanical Data

- Case: TO-277B Molded Plastic "Green" Molding Compound
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Weight: 0.093 grams (approx.)
- Mounting Position: Any
- Marking: Type Number
- Lead Free: For RoHS/Lead Free Version

Maximum Ratings and Electrical Characteristics @ $T_A=25^\circ\text{C}$ unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

| Characteristic | Symbol | SR15T80L | SR15T100L | SR15T120L | SR15T150L | SR15T200L | Unit | |
|---|-----------------|---------------------|---------------------|---------------------|---------------------|------------------------|------|---------------------------|
| Peak Repetitive Reverse Voltage | V_{RRM} | 80 | 100 | 120 | 150 | 200 | V | |
| Working Peak Reverse Voltage | V_{RWM} | | | | | | | |
| DC Blocking Voltage | V_R | | | | | | | |
| RMS Reverse Voltage | $V_{R(RMS)}$ | 56 | 70 | 84 | 105 | 140 | V | |
| Average Rectified Output Current @ $T_L = 100^\circ\text{C}$ (Note 1) | I_o | 15 | | | | | | A |
| Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method) | I_{FSM} | 300 | | | | | | A |
| I^2t Rating for Fusing ($t < 8.3\text{ms}$) | I^2t | 373.5 | | | | | | A^2s |
| Forward Voltage Drop $T_A = 25^\circ\text{C}$ @ $I_F = 1.0\text{A}$ $T_A = 25^\circ\text{C}$ @ $I_F = 5.0\text{A}$ $T_A = 25^\circ\text{C}$ @ $I_F = 15\text{A}$ | V_{FM} | Typ. 0.37 Max. - | Typ. 0.37 Max. - | Typ. 0.43 Max. - | Typ. 0.60 Max. - | Typ. 0.71 Max. 0.75 | 0.80 | V |
| Peak Reverse Current @ $T_A = 25^\circ\text{C}$ At Rated DC Blocking Voltage @ $T_A = 100^\circ\text{C}$ | I_{RM} | 0.3 15 | | | | | | mA |
| Typical Thermal Resistance (Note 1) | $R_{\theta JA}$ | 110 | | | | | | $^\circ\text{C}/\text{W}$ |
| Operating and Storage Temperature Range | T_j, T_{STG} | -55 to +150 | | | | | | $^\circ\text{C}$ |

Note: 1. Valid provided that leads are kept at ambient temperature at a distance of 9.5mm from the case.
2. FR-4 PCB, 2oz. Copper, minimum recommended pad layout .
3. Polyimide PCB, 2oz. Copper. Cathode pad dimensions 18.8mm x 14.4mm. Anode pad dimensions 5.6mm x 14.4mm.

FIG.1 - FORWARD

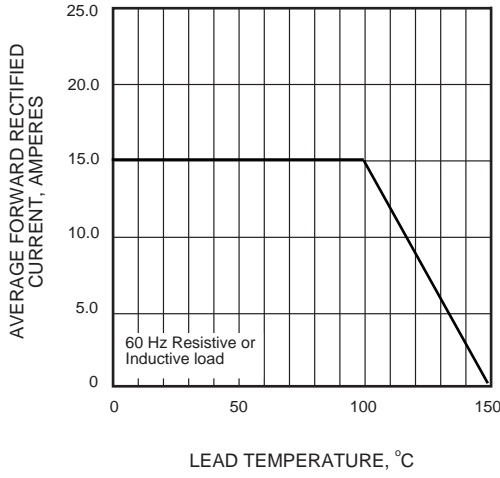


FIG.2 - TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

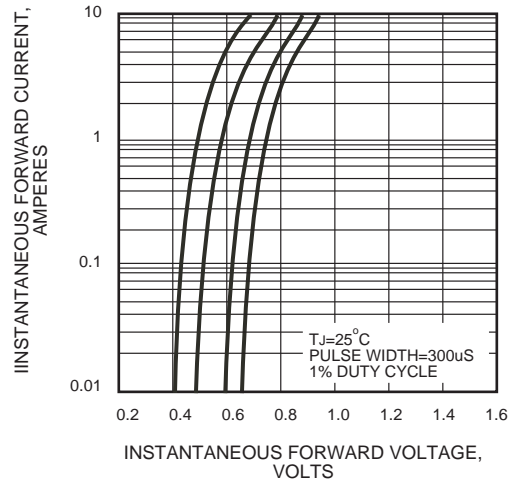


FIG.3 - MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

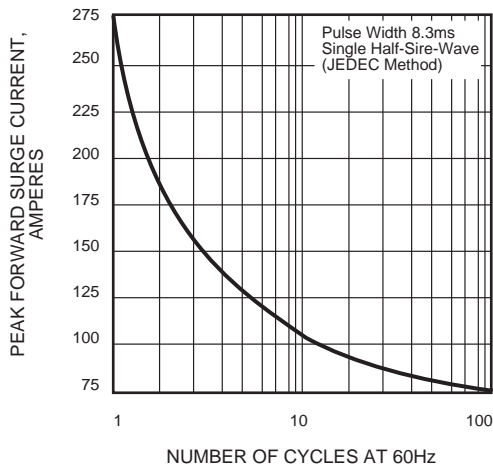


FIG.4 - TYPICAL REVERSE CHARACTERISTICS

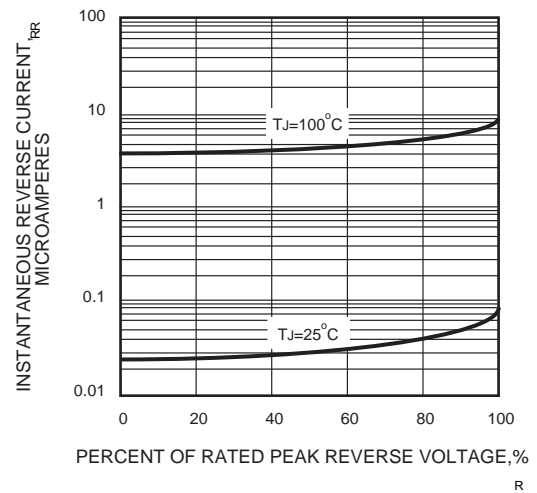


FIG.5 - TYPICAL JUNCTION CAPACITANCE

